

## Product Change Notice

Issue Date: 5 March, 2024

**Change Type:**

New Wafer Sort Test Floor (K27) at ASE-KH

**Parts Affected:**

BCM89230B1BCFBGT  
BCM89230B1BCFBG  
BCM89230B2BCFBG  
BCM89231B1BPBGT  
BCM89231B1BPBG  
BCM89530B1BPBGT  
BCM89530B1BPBG  
BCM89531B1BPBGT  
BCM89531B1BPBG  
BCM89531B2BPBG  
BCM89535B1BPBG  
BCM89241B1BFBG  
BCM89251B1BFBG  
BCM89251B1BFBG  
BCM89251B2BFBG  
BCM89541B1BFBG  
BCM89541B1BFBG  
BCM89541B2BFBG  
BCM89550B1BFBG  
BCM89550B2BFBG  
BCM89551B1BFBG  
BCM89551B1BFBG  
BCM89551B2BFBG

**Description and Extent of Change:**

Electrical wafer sort testing is currently performed on this product at ASE-KH (Kaohsiung City, Taiwan R.O.C.). ASE-KH is expanding wafer sort capacity to a new test floor – K27. There will be **no change** to the:

- QMS System
- Wafer Sort Flow
- Environmental Controls
- Control Plan
- Testers / Test Hardware / Test Software

There is no change to Foundry, Assembly or Final Test for this PCN.

**Reasons for Change:**

Increase wafer sort capacity

**Effect of Change on Fit, Form, Function, Quality, or Reliability:**

The device specification, test limits, SYA/SBL limits, and D-PAT will remain the same, which will ensure product electrical performance remains the same. Appropriate correlation has been performed to ensure **no impact** on Fit, Form, Function, Quality, or Reliability. In addition, the devices are fully tested at Hot and Cold temperature at Final Test.

**Effective Date of Change:**

Product shipments using this change will begin after **15-Aug-2024**. Timing of shipment of parts tested at ASE-KH (K27) will vary by part number depending on customer demand and inventory levels.

**Correlation Information:**

The correlation activity has successfully completed. See the table below for details.

Correlation Item	ASE-KH (K27) Result		
	BCM8923x/BCM8953x	BCM89241/BCM89251/ BCM89541/BCM8955x	OK/ NOK
Tester	Same as at existing test floor	Same as at existing test floor	OK
Test DIB and probe card	Same as at existing test floor	Same as at existing test floor	OK
Test Program	Same as at existing test floor	Same as at existing test floor	OK
Test time / # of tests	Same as at existing test floor	Same as at existing test floor	OK
SYA/SBL limits	Same as at existing test floor	Same as at existing test floor	OK
D-PAT limits	Same as at existing test floor	Same as at existing test floor	OK
Loop 50 times; 5 units/site @ Room Temp	1500/1500 pass	1500/1500 pass	OK
Run 1 correlation wafer (yield/reject comparison) @ Room Temp	Pass	Pass	OK
Analog test parameter correlation	Pass	Pass	OK

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.